fabricated on nearly any substrate and is cheap to manufacture. The resultant product is a reliable, portable power source with steady output over extended periods or rain or shine, night or day, warm or cold.

[0257] According to the present invention, solid-state processes are used to cofabricate direct energy conversion materials and energy storage on the same substrate. This is possible by using the low-temperature processes for solid-state batteries described above.

[0258] **FIG. 24B** shows a block diagram of a battery-layer-deposition system **2460**. In some embodiments, system **2460** includes a supply reel **2461**, a deposition chamber **2462** that deposits one or more layers of battery **2320** onto a substrate **2410** as described above, and a takeup reel **2463**. Typically, deposition chamber **2462** is a vacuum chamber that encloses supply reel **2461** and takeup reel **2463**, and successively deposits a plurality of layers, wherein each of one or more of the layers is immediately treated (e.g., by ion assist, laser surface anneal, heat surface anneal, or kinetic treatment), according to the present invention, to impart a high-quality surface structure to that layer or those layers before subsequent layers are deposited, and without substantial heating of the underlying layer(s) or substrate. For layers that need to be thicker, a longer deposition station is provided than the station for thinner layers. In some embodiments, the lower contact layer **2322** is deposited onto a starting substrate film, fabric, or foil **2410**, then the cathode, electrolyte, anode, and anode-contact layers are deposited, wherein the cathode layer and/or the electrolyte layer are treated (e.g., by an ion-assist beam) before subsequent layers are deposited.

[0259] **FIG. 24C** shows the resulting item **2464**, which is a continuous sheet of substrate material **2410** having batteries **2320** deposited on it. This partially built item **2464** is then used as the supply reel **2466** of layer-deposition system **2465** of **FIG. 24D**. **FIG. 24D** shows a block diagram of a energy-conversion-layer-deposition system **2465**. In some embodiments, system **2565** deposits layers that form a photovoltaic cell **2430** onto battery **2320** of **FIG. 24A**. In some embodiments, system **2460** and system **2465** are merged into a single system having a single supply reel **2461** and a single takeup reel **2468**, and having layers of the battery **2320** and of the photovoltaic cell **2430** successively deposited. In other embodiments, other types of devices **2430** are deposited such as capacitors, antennae, circuitry, transducers, sensors, magneto-resistors (e.g., of the giant magneto-resistor type), etc.

[0260] **FIG. 24E** shows a perspective view of a processed sheet **2469** that is the result of processing be system **2460** and system **2465**. Sheet **2469** is then cut or diced into individual devices **2400**. **FIG. 24F** shows a perspective view of three diced final devices **2400**. In other embodiments, sheet **2469** is cut into any desired number of devices **2400**.

[0261] In other embodiments, system **2460** and system **2465** deposit a battery **2320** and a photovoltaic cell **2330** side-by-side on one face of substrate **2310**, such as shown in **FIG. 22**G and **FIG. 22H**. In some such embodiments, one or more of the layers deposited for battery **2320** are also deposited for photovoltaic cell **2330** simultaneously of the same deposition material, thus saving process steps but making a wider device than if stacked as in **FIG. 24A**.

[0262] **FIG. 25A** shows a perspective view of an embodiment **2500** of the present invention having an integrated circuit **2510** overlaid with a battery **2320**. In some embodiments, integrated circuit **2510** includes a top insulator layer **2511** having a plurality of vias or openings **2512** to the active surface of the integrated circuit **2510** (the side with devices and connectors). Two of these vias are used as contacts **2514** and **2515** between integrated circuit **2510** and battery **2320**. Battery **2320** is deposited as described for **FIG. 23**. In some embodiments, battery **2320** is deposited on an integrated circuit wafer before integrated circuit **2510** is diced apart from the other integrated circuits. In some embodiments, battery **2320** is deposited onto integrated circuit **2510** after integrated circuit **2510** is diced apart from the other integrated circuits. Some embodiments further include a passivation layer over the top and sides of battery **2320** such as layer **2331** of **FIG. 23**.

[0263] In other embodiments, a circuit such as circuit **2330** of **FIG. 23** is used in place of integrated circuit **2510** of **FIG. 25A**. Thus, a pattern of vias and/or other devices or circuitry is deposited on a substrate, and battery **2320** is deposited on the top of the predefined circuitry/substrate, as in **FIG. 25A**. In some embodiments, a photovoltaic cell is used as such a circuit device/substrate, and battery **2320** is deposited directly on the premanufactured photovoltaic cell. In some embodiments, an integrated circuit such as **2440** of **FIG. 24A** is wired to the battery **2320** and the premanufactured photovoltaic cell to control charging of the battery from the cell and/or to control using power for other devices (such as a light source or hearing aid) from the photocell during periods of high amounts of light and power available from the photovoltaic cell, and using power from the battery during periods of little or no light and power available from the photovoltaic cell.

[0264] Virtually all electronics require energy to operate and perform the designed functions. This energy typically comes from either an AC source such as a home wall electrical outlet or a battery mounted in the packaging of the electronic device. Until the last few years, this approach has proved to be acceptable even though the inefficiencies caused waste of both energy and natural resources in that the device housing had to be made large enough to incorporate the energy package or conversion electronics. As electronic complexity increases, the wasted real estate and energy begin to become an issue as the demands of operator interface begin to compete with the energy source for area on the device. The application of the solid-state battery process of the present invention allows the cofabricating of electronics and the associated power source together on chip.

[0265] Solid-state processes are used to cofabricate electronics and solid-state rechargeable battery on a common substrate such as silicon used for IC processing. This is possible by using the low-temperature processes for solid-state batteries described above.

[0266] Referring to **FIG. 25A**, in some embodiments, the integrated circuit (IC) **2510** in wafer form is processed normally through final passivation including bond-pad etch. All thermal processing necessary for the electronics is performed conventionally. The IC in wafer form is sent to backend energy processing. In some embodiments, the design of the IC includes electronics for control of recharge for the solid-state energy source; contact vias for connecting the cathode plate and anode plate to the circuit. Using